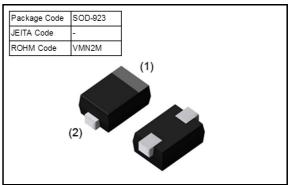


Zener Diode Data sheet

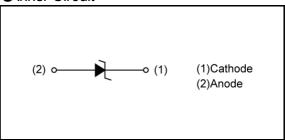
P_{D}	100	mW

Outline



FeatureHigh reliabilitySmall mold type

Inner Circuit



ApplicationVoltage regulation

Packaging Specification

T ackaging Specification				
Packing	Embossed Tape			
Reel Size(mm)	180			
Taping Width(mm)	8			
Basic Ordering Unit(pcs)	8000			
Taping Code	T2R			
Marking	L			

StructureSilicon Epitaxial Planar

● Absolute Maximum Rating (T_a = 25°C)

Parameter	Symbol	Limits	Unit
Power dissipation	P_{D}	100	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 ∼ 150	ဇ

● Characteristic (T_a = 25°C)

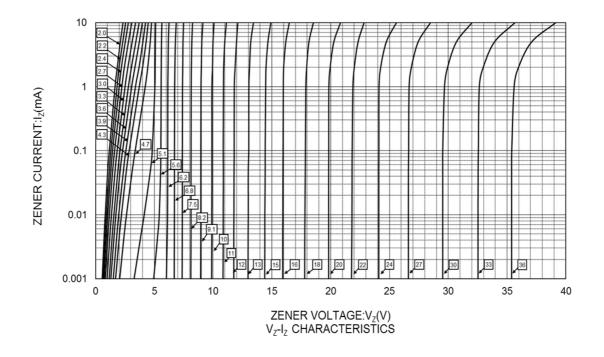
					Symbol				
P/N	Zen	Zener Voltage:V _Z (V)		Dynamic Impedance: $Z_Z(\Omega)$		Zener Impedance: $Z_{ZK}(\Omega)$		Reverse Current:I _R (µA)	
	MIN.	MAX.	I _z (mA)	MAX.	l _z (mA)	MAX.	I _z (mA)	MAX.	V _R (V)
CDZV 2.0B	2.020	2.200	5.0	100	5.0	1000	0.5	120	0.5
CDZV 2.2B	2.220	2.410	5.0	100	5.0	1000	0.5	120	0.7
CDZV 2.4B	2.430	2.630	5.0	100	5.0	1000	0.5	120	1.0
CDZV 2.7B	2.690	2.910	5.0	110	5.0	1000	0.5	100	1.0
CDZV 3.0B	3.010	3.220	5.0	120	5.0	1000	0.5	50	1.0
CDZV 3.3B	3.320	3.530	5.0	120	5.0	1000	0.5	20	1.0
CDZV 3.6B	3.600	3.845	5.0	100	5.0	1000	1.0	10	1.0
CDZV 3.9B	3.890	4.160	5.0	100	5.0	1000	1.0	5.0	1.0
CDZV 4.3B	4.170	4.430	5.0	100	5.0	1000	1.0	5.0	1.0
CDZV 4.7B	4.550	4.750	5.0	100	5.0	800	0.5	2.0	1.0
CDZV 5.1B	4.980	5.200	5.0	80	5.0	500	0.5	2.0	1.5
CDZV 5.6B	5.490	5.730	5.0	60	5.0	200	0.5	1.0	2.5
CDZV 6.2B	6.060	6.330	5.0	60	5.0	100	0.5	1.0	3.0
CDZV 6.8B	6.650	6.930	5.0	40	5.0	60	0.5	0.5	3.5
CDZV 7.5B	7.280	7.600	5.0	30	5.0	60	0.5	0.5	4.0
CDZV 8.2B	8.020	8.360	5.0	30	5.0	60	0.5	0.5	5.0
CDZV 9.1B	8.850	9.230	5.0	30	5.0	60	0.5	0.5	6.0
CDZV 10B	9.770	10.210	5.0	30	5.0	60	0.5	0.1	7.0
CDZV 11B	10.760	11.220	5.0	30	5.0	60	0.5	0.1	8.0
CDZV 12B	11.740	12.240	5.0	30	5.0	80	0.5	0.1	9.0
CDZV 13B	12.910	13.490	5.0	37	5.0	80	0.5	0.1	10.0
CDZV 15B	14.340	14.980	5.0	42	5.0	80	0.5	0.1	11.0
CDZV 16B	15.850	16.510	5.0	50	5.0	80	0.5	0.1	12.0
CDZV 18B	17.560	18.350	2.0	65	2.0	80	0.5	0.1	13.0
CDZV 20B	19.520	20.390	2.0	85	2.0	100	0.5	0.1	15.0
CDZV 22B	21.540	22.470	2.0	100	2.0	100	0.5	0.1	17.0
CDZV 24B	23.720	24.780	2.0	120	2.0	120	0.5	0.1	19.0
CDZV 27B	26.190	27.530	2.0	150	2.0	150	0.5	0.1	21.0
CDZV 30B	29.190	30.690	2.0	200	2.0	200	0.5	0.1	23.0
CDZV 33B	32.150	33.790	2.0	250	2.0	250	0.5	0.1	25.0
CDZV 36B	35.070	36.870	2.0	300	2.0	300	0.5	0.1	27.0

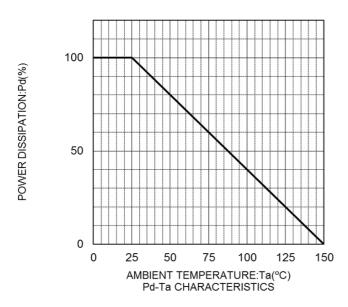
V_Z test time is 40ms.

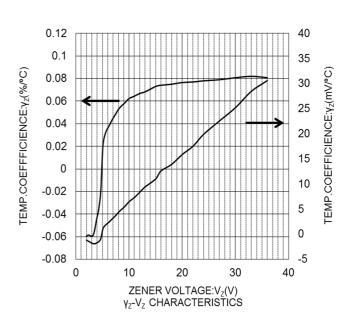
Marking

P/N	Marking	P/N	Marking
CDZV 2.0B	P	CDZV 9.1B	J
CDZV 2.2B	Q	CDZV 10B	K
CDZV 2.4B	R	CDZV 11B	L
CDZV 2.7B	2	CDZV 12B	N
CDZV 3.0B	S	CDZV 13B	S
CDZV 3.3B	9	CDZV 15B	C
CDZV 3.6B	7	CDZV 16B	E
CDZV 3.9B	1	CDZV 18B	1
CDZV 4.3B	2	CDZV 20B	3
CDZV 4.7B	3	CDZV 22B	5
CDZV 5.1B	5	CDZV 24B	F
CDZV 5.6B	7	CDZV 27B	H
CDZV 6.2B	С	CDZV 30B	K
CDZV 6.8B	E	CDZV 33B	Ĺ
CDZV 7.5B	F	CDZV 36B	N
CDZV 8.2B	Н		

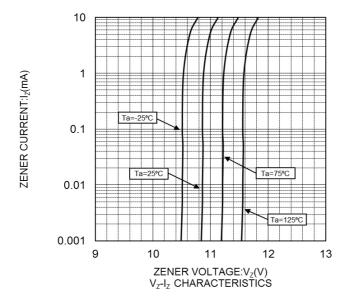
Characteristic Curves

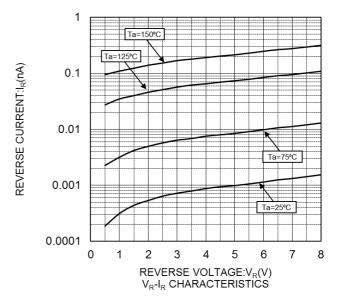


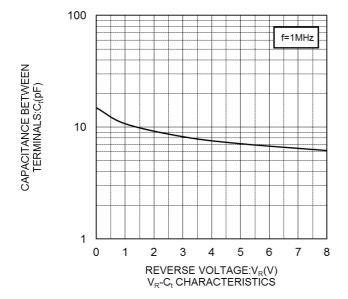


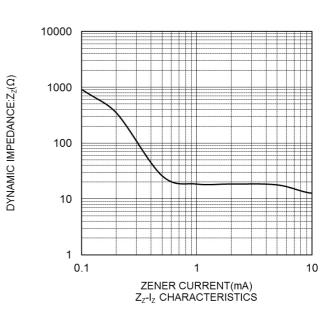


Characteristic Curves

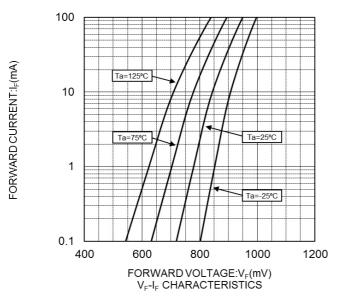


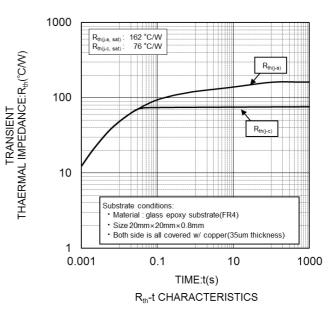




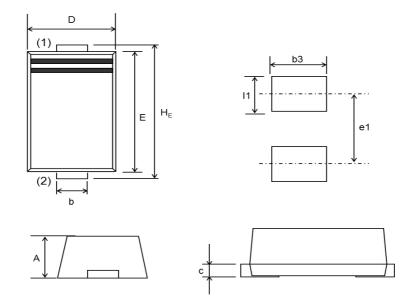


Characteristic Curves





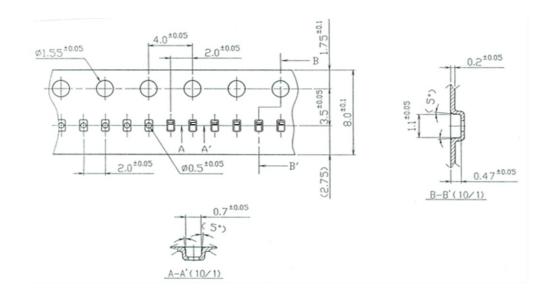
● Dimension (VMN2M)



DIM	DIM Milim eters		Inches			
DIIVI	Min.	Average	Max.	Min.	Average	Max.
Α	0.34	0.37	0.40	0.013	0.015	0.016
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.11	0.16	0.21	0.004	0.006	0.008
D	0.55	0.60	0.65	0.022	0.024	0.026
E	0.81	0.86	0.91	0.032	0.034	0.036
HE	0.95	1.00	1.05	0.037	0.039	0.041
I1	-	0.45	ı	-	0.018	ı
b3	-	0.55	-	-	0.022	-
e1	-	0.95	- 1	-	0.037	-

- (1) The marking bar indicates the cathode.
- (2) The direction indicates the anode.

● Taping (Unit:mm)



Notice

Precaution on using ROHM Products

1. Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA	
CLASSⅢ	CL ACCIII	CLASS II b	CL A C C TT	
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ	

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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